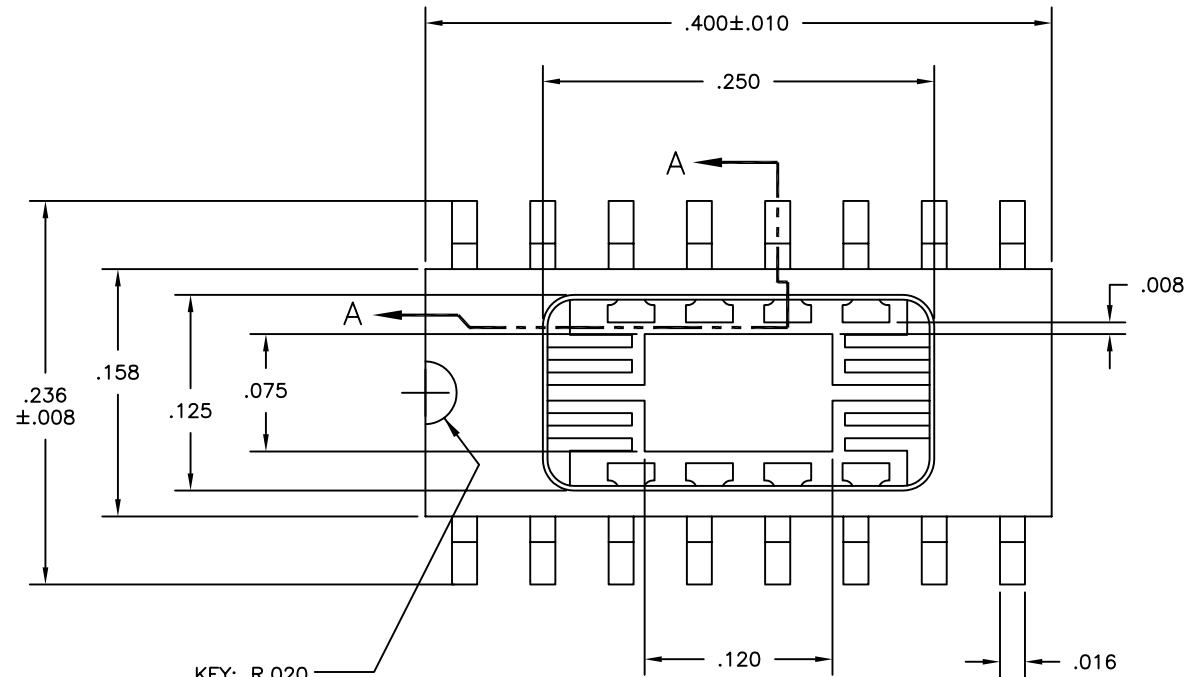
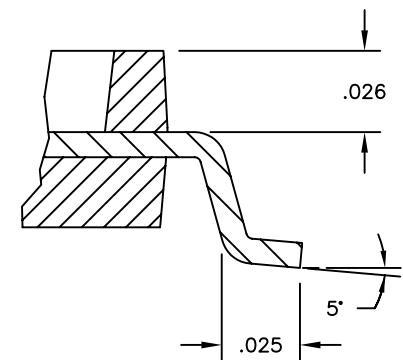


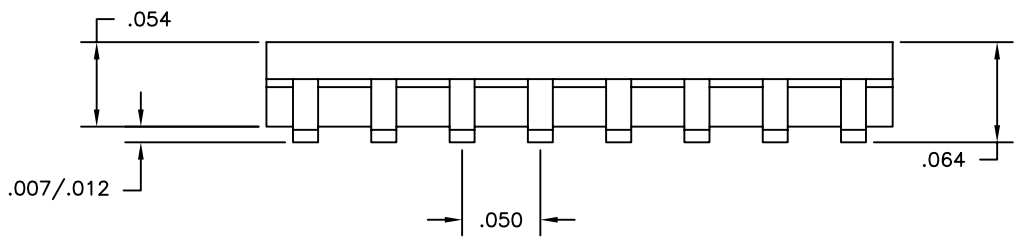
REVISIONS			
ECN NO.	DATE	DESCRIPTION	APPROVED
10789	11/01/06	PRODUCTION RELEASE	D.BENANDO



KEY: R.020
0.018 DEEP



SECTION A-A
SCALE: 2/1



- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE
 2. LEAD FRAME: COOPER, 194 FH
 3. LEAD FINISH: FULL Au
 4. FRAME THICKNESS: .0080 ± 0.0003
 5. DIE PAD: .075 X .120
 6. JEDEC OUTLINE: MS-012

THIRD ANGLE PROJECTION

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ARE:
X.XX ± 0.01 X.XXXX ± ---
X.XXX ± 0.005 ANGLES: ± 1'

DO NOT SCALE DRAWING

DRAWN BY	C. CRUZ	DATE	11/01/06
APP BY	P. FLASKERUD	DATE	11/01/06
CUSTOMER	---		
THIS DOCUMENT CONTAINS INFORMATION PROPRIETARY TO SEMPAC, INC., AND REPRODUCTION OR ISSUE IN ANY FORM IS NOT PERMITTED WITHOUT WRITTEN AUTHORITY FROM SEMPAC, INC.			

SEMPAC, INC. Open-Pak™ Technologies www.sempac.com 568 E. WEDDELL DRIVE, SUITE 5 SUNNYVALE, CALIFORNIA 94089 PHONE: (408) 400-9002 FAX: (408) 400-9006			
16 Lead 150 mils SOIC Open-Pak			
SIZE	PART NO.	REV	
A	SOIC150-16-OP-01	4	
SCALE	CAD FILE	SHEET	
NONE	SOIC150-16-OP-01-R4.DWG	1 OF 1	